

**SUPPLEMENT NO. 7 TO PART 748 - AUTHORIZATION VALIDATED END-USER (VEU): LIST OF VALIDATED END-USERS, RESPECTIVE ITEMS ELIGIBLE FOR EXPORT, REEXPORT AND TRANSFER, AND ELIGIBLE DESTINATIONS**

<b>Country</b>	<b>Validated End-User</b>	<b>Eligible Items (By ECCN)</b>	<b>Eligible Destination</b>	<b>Federal Register Citation</b>
<b>China (People's Republic of)</b>	Advanced Micro Devices China, Inc.	3D002, 3D003, 3E001 (limited to "technology" for items classified under 3C002 and 3C004 and "technology" for use during the International Technology Roadmap for Semiconductors (ITRS) process for items classified under ECCNs 3B001 and 3B002), 3E002 (limited to "technology" for use during the ITRS process for items classified under ECCNs 3B001 and 3B002), 3E003.e (limited to the "development" and "production" of integrated circuits for commercial applications), 4D001, 4D002, 4D003 and 4E001 (limited to the "development" of products under ECCN 4A003).	AMD Technologies (China) Co., Ltd No. 88, Su Tong Road, Suzhou, China 215021.  Advanced Micro Devices (Shanghai) Co., Ltd. Buildings 46, 47, 48 & 49, River Front Harbor Zhangjiang Hi-Tech Park 1387 Zhangdong Rd., Pudong, Shanghai, 201203.  AMD Technology Development (Beijing) Co., Ltd. 18F, North Building Raycom Infotech Park Tower C, No. 2 Science Institute South Rd., Zhong Guan Cun, Haidian District, Beijing, China 100190.	75 FR 25763, 5/10/10.  76 FR 2802, 1/18/11.
	Applied Materials (China), Inc.	2B006.b, 2B230, 2B350.g.3, 2B350.i, 3B001.a, 3B001.b, 3B001.c, 3B001.d, 3B001.e, 3B001.f, 3C001, 3C002, 3D002 (limited to "software" specially designed for the "use" of stored program controlled items classified under ECCN 3B001).	Applied Materials South East Asia Pte. Ltd. - Shanghai Depot c/o Shanghai Applied Materials Technical Service Center No. 2667 Zuchongzhi Road, Shanghai, China 201203.  Applied Materials South East Asia Pte. Ltd. - Beijing Depot c/o Beijing Applied Materials Technical Service Center No. 1 North Di Sheng Street,	72 FR 59164, 10/19/07.  74 FR 19382, 4/29/09.  75 FR 27185, 5/14/10.  77 FR 10953, 2/24/12.

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			<p>BDA Beijing, China 100176.</p> <p>Applied Materials South East Asia Pte. Ltd. - Wuxi Depot c/o Sinotrans Jiangsu Fuchang Logistics Co., Ltd. 1 Xi Qin Road, Wuxi Export Processing Zone Wuxi, Jiangsu, China 214028.</p> <p>Applied Materials South East Asia Pte. Ltd. - Wuhan Depot c/o Wuhan Optics Valley Import &amp; Export Co., Ltd. No. 101 Guanggu Road East Lake High-Tec Development Zone Wuhan, Hubei, China 430074.</p> <p>Applied Materials (China), Inc. - Shanghai Depot No. 2667, Zuchongzhi Road Shanghai, China 201203.</p> <p>Applied Materials (China), Inc. - Beijing Depot No. 1 North Di Sheng Street, BDA Beijing, China 100176.</p>	

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		2B006.b, 2B230, 2B350.g.3, 2B350.i, 3B001.a, 3B001.b, 3B001.c, 3B001.d, 3B001.e, 3B001.f, 3C001, 3C002, 3D002 (limited to “software” specially designed for the “use” of stored program controlled items classified under ECCN 3B001), and 3E001 (limited to “technology” according to the General Technology Note for the “development” or “production” of items controlled by ECCN 3B001).	Applied Materials (Xi’an) Ltd. No. 28 Xin Xi Ave., Xi’an High Tech Park Export Processing Zone Xi’an, Shaanxi, China 710075.	
	Boeing Tianjin Composites Co. Ltd.	1A002.a, 1B001.f, 1C010.b, 1C010.e, 1D001 (limited to “software” specially designed or modified for the “development”, “production” or “use” of equipment controlled by 1B001.f), 1E001 (limited to “technology” according to the General Technology Note for the “development” or “production” of items controlled by 1A002.a, 1B001.f, and 1C010.b & .e), 2B001.b.2 (limited to machine tools with accuracies no better than (i.e., less than) 13 microns), 2B001.e, 2D001 (limited to “software,” other than that controlled by 2D002, specially designed or modified for the “development”, “production” or “use” of	Boeing Tianjin Composites Co. Ltd. No. 4-388 Heibei Road Tanggu Tianjin, China.	72 FR 59164, 10/19/07. 74 FR 19382, 4/29/09. 77FR 10953, 2/24/12.

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		equipment controlled by 2B001.b.2 and 2B001.e), and 2D002 (limited to “software” for electronic devices, even when residing in an electronic device or system, enabling such devices or systems to function as a “numerical control” unit, capable of coordinating simultaneously more than 4 axes for “contouring control” controlled by 2B001.b.2 and 2B001.e).		
	CSMC Technologies Corporation	1C350.c.3, 1C350.c.11, 2B230.a, 2B230.b, 2B350.f, 2B350.g, 2B350.h, 3B001.c.1.a, 3B001.c.2.a, 3B001.e 3B001.h (except for multilayer masks with a phase shift layer designed to produce “space qualified” semiconductor devices), 3C002.a, and 3C004.	<p>CSMC Technologies Fab 1 Co., Ltd. 14 Liangxi Road Wuxi, Jiangsu 214061, China.</p> <p>CSMC Technologies Fab 2 Co., Ltd. 8 Xinzhou Rd. Wuxi National New Hi-Tech Industrial Development Zone Wuxi, Jiangsu 214061, China.</p> <p>Wuxi CR Semiconductor Wafers and Chips Co., Ltd., 14 Liangxi Road Wuxi, Jiangsu 214061, China.</p>	<p>76 FR 2802, 1/18/11.</p> <p>76 FR 37634, 6/28/11.</p> <p>77 FR 10953, 2/24/12</p>

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	Grace Semiconductor Manufacturing Corporation.	1C350.c.3, 1C350.d.7, 2B230, 2B350.d.2, 2B350.g.3, 2B350.i.4, 3B001.a.1, 3B001.b, 3B001.c, 3B001.d, 3B001.e, 3B001.f, 3B001.h, 3C002, 3C004, 5B002, and 5E002 (limited to production technology for integrated circuits controlled by ECCNs 5A002 or 5A992 that have been successfully reviewed under the encryption review process specified in sections 740.17(b)(2) or 740.17(b)(3) and 742.15 of the EAR; Note also the guidance on cryptographic interfaces (OCI) in section 740.17(b) of the EAR).	1399 Zuchongzhi Road Zhangjiang Hi-Tech Park Shanghai, PR China 201203.	75 FR 2435, 1/15/10.
	Hynix Semiconductor China Ltd.	3B001.a, 3B001.b, 3B001.c, 3B001.d, 3B001.e, and 3B001.f.	Hynix Semiconductor China Ltd. Lot K7/K7-1, Export Processing Zone Wuxi, Jiangsu, PR China.	75 FR 62462, 10/12/10.
	Hynix Semiconductor (Wuxi) Ltd	3B001.a, 3B001.b, 3B001.c, 3B001.d, 3B001.e, and 3B001.f.	Hynix Semiconductor (Wuxi) Ltd., Lot K7/K7-1, Export Processing Zone, Wuxi, Jiangsu, PR, China.	75 FR 62462, 10/12/10.
	Lam Research Corporation	2B230, 2B350.c, 2B350.d, 2B350.g, 2B350.h, 2B350.i, 3B001.c and 3B001.e (items classified under ECCNs 3B001.c and 3B001.e are limited to parts and components), 3D001 and 3D002 (items classified under ECCNs 3D001 and 3D002 are limited to “software” specially designed for the “use” of stored program controlled items classified under	Lam Research (Shanghai) Service Co. 1st Floor, Area C Hua Hong Science & Technology Park, 177 Bi Bo Road Zhangjiang Hi-Tech Park Pudong, Shanghai, China 201203.  Lam Research Shanghai Co., Ltd. No. 1 Jilong Rd.	75 FR 62462, 10/12/10. 77 FR 10953, 2/24/12.

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		ECCN 3B001), and 3E001 (limited to “technology” according to the General Technology Note for the “development” of equipment controlled by ECCN 3B001).	<p>Room 424-2 Waigaoqiao Free Trade Zone Shanghai, China 200131.</p> <p>Lam Research International Sarl (Lam Shanghai Warehouse) c/o HMG Supply Chain (Shanghai) Co., Ltd. No.3869, Longdong Avenue Pudong New District Shanghai, China 201203.</p> <p>Lam Research International Sarl (Lam Shanghai Warehouse; WGQ Bonded Warehouse) c/o HMG Supply Chain (Shanghai) Co., Ltd. No.55, Fei la Road, Waigaoqiao Free Trade Zone, Pudong New Area, Shanghai, China 200131.</p> <p>Lam Research Service Co., Ltd. (Beijing Branch) Rm 1010, Zhaolin Building No. 15 Rong Hua Zhong Road BDA, Beijing, China 100176.</p> <p>Lam Research International Sarl (Lam Beijing Warehouse) Beijing Lam Electronics Tech Center, No. 8 Building, No.1, Disheng North Street, BDA, Beijing, China 100176.</p> <p>Lam Research Service Co., Ltd.</p>	

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			<p>Wuxi Representative Office Singapore International Park 6 #302, No. 89 Xing Chuang 4 Road, New District Wuxi, Jiangsu, China 214028.</p> <p>Lam Research International Sarl (Wuxi EPZ Bonded Warehouse) c/o HMG WHL Logistic (Wuxi) Co., Ltd. F1, Area 4, No. 1, Plot J3 No. 5 Gaolang East Road Export Processing Zone Wuxi, China 214028.</p> <p>Lam Research Service Co., Ltd. Wuhan Representative Office No. 1 Guanshan Road Donghu Development Zone Room E4-302, Optical Valley Software Park Wuhan, Hubei, China 430074.</p> <p>Lam Research Semiconductor (Suzhou) Co., Ltd. (Suzhou) A Division of Lam Research International Sarl A-2 Building, Export Processing Zone Suzhou New District Jiangsu Province, China 215151.</p> <p>Lam Research International Sarl (Lam Beijing Warehouse)</p>	

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			<p>Building 3, No. 9 Ke Chuang Er Street Beijing Economic Technology Development Zone Beijing, China 100176.</p> <p>Lam Research International Sarl (Wuhan TSS) c/o HMG Wuhan Logistic Co., Ltd. 1st – 2nd Floor, No. 5 Building Hua Shi Yuan Er Road Optical Valley Industry Park East-lake Hi-Tech Development Zone Wuhan City, Hubei Province, China 430223.</p>	



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	Semiconductor Manufacturing International Corporation	Items controlled under ECCNs 1C350.c.3, 1C350.d.7, 2B006.b.1, 2B230, 2B350.d.2, 2B350.g.3, 2B350.i.3, 3B001.a, 3B001.b, 3B001.c, 3B001.d, 3B001.e, 3B001.f, 3C001, 3C002, 3C004, 5B002 and 5E002 (limited to “technology” according to the General Technology Note for the “production” of integrated circuits controlled by ECCN 5A002 that have been classified by BIS as eligible for License Exception ENC under paragraph (b)(2) or (b)(3) of section 740.17 of the EAR, or classified by BIS as a mass market item under paragraph (b)(3) of section 742.15 of the EAR).	<p>Semiconductor Manufacturing International (Shanghai) Corporation, 18 Zhang Jiang Rd., Pudong New Area, Shanghai, China 201203.</p> <p>Semiconductor Manufacturing International (Tianjin) Corporation, 19 Xing Hua Avenue, Xi Qing Economic Development Area, Tianjin, China 300385.</p> <p>Semiconductor Manufacturing International (Beijing) Corporation, No. 18 Wen Chang Road, Beijing Economic-Technological Development Area, Beijing, China 100176.</p>	<p>72 FR 59164, 10/19/07.</p> <p>75 FR 67029, 11/1/10.</p> <p>77 FR 10953, 2/24/12.</p>

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	Shanghai Hua Hong NEC Electronics Company, Ltd.	1C350.c.3; 1C350.d.7; 2B230; 2B350.d.2 2B350.g.3 2B350.i.4; 3B001.c.2; 3C002; 3C004.	Headquarters and Fab. 1 of HHNEC, No. 1188 Chuan Qiao Rd., Pu Dong, Shanghai, China 201206.  Fab. 2 of HHNEC No. 668 Guo Shou Jing Rd., Zhang Jiang High Tech Park, Pu Dong, Shanghai, China 201203.	72 FR 59164, 10/19/07.
<b>India</b>	GE India Industrial Pvt Ltd.	1C002.a.1, 1C002.a.2, 1C002.b.1.a, 1C002.b.1.b, 1E001, 2E003.f, 9E003.a.1, 9E003.a.2, 9E003.a.4, 9E003.a.5, 9E003.a.6, 9E003.a.8, and 9E003.c.	GE India Technology Centre Private Limited (GEITC) No. 122, EPIP, Phase II Hoodi Village, Whitefield Road Bangalore 560066, Karnataka, India.  Bangalore Engineering Center (BEC) c/o GE India Technology Centre Private Limited (GEITC) No. 122, EPIP, Phase II Hoodi Village, Whitefield Road Bangalore 560066, Karnataka, India.	74 FR 31620, 7/2/09.  74 FR 68147, 12/23/09.  77 FR 10953, 2/24/12.